

ESDALC6V1-1BM2

Single line low capacitance TRANSIL[™] for ESD protection

Applications

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Cellular phone handsets and accessories
- Video equipment

Features

- 1 line low capacitance TRANSIL diode
- Bidirectional ESD protection
- Breakdown Voltage V_{BR} = 6.1 V min.
- Low diode capacitance (22 pF typ. at 0 V)
- Low leakage current: < 100 nA at 3 V
- Very small PCB area: 0.6 mm²
- Leadfree package

Description

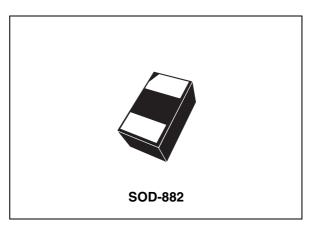
The ESDALC6V1-1BM2 is a bidirectional single line TVS diode designed to protect the datalines or other I/O ports against ESD transients.

The device is ideal for applications where both reduced line capacitance and board space saving are required.

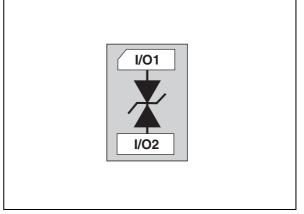
Benefits

- High ESD protection level
- High integration
- Suitable for high density boards

TM: TRANSIL is a trademark of STMicroelectronics



Functional diagram



Order code

| Part number | Marking | | |
|----------------|---------|--|--|
| ESDALC6V1-1BM2 | Р | | |

Complies with the following standards:

IEC 61000-4-2 level 4

15 kV (air discharge)

8 kV (contact discharge)

MIL STD 883E - Method 3015-7: class 3

HBM (Human body model)

1 Characteristics

| Symbol | Parameter | Value | Unit | | | | |
|--------------------------------|---|---------------|------|--|--|--|--|
| V _{PP} ⁽¹⁾ | Peak pulse voltage (IEC 61000-4-2 contact c | ± 30 | kV | | | | |
| P _{PP} ⁽¹⁾ | Peak pulse power dissipation (8/20 µs) | 140 | W | | | | |
| I _{PP} | Repetitive peak pulse current (8/20 µs) | 9 | А | | | | |
| Тj | Junction temperature | 125 | °C | | | | |
| T _{stg} | Storage temperature range | - 55 to + 150 | °C | | | | |
| ΤL | Maximum lead temperature for soldering dur | 260 | °C | | | | |
| T _{OP} | Operating temperature range | - 40 to + 125 | °C | | | | |

Table 1. Absolute maximum ratings ($T_{amb} = 25^{\circ} C$)

1. For a surge greater than the maximum values, the diode will fail in short-circuit.

Table 2.Electrical characteristics ($T_{amb} = 25^{\circ}$ C)

| Symbol | Parameter | 1 |
|-----------------|-----------------------------------|---------|
| V _{RM} | Stand-of voltage | |
| V _{BR} | Breakdown voltage | - In |
| V _{CL} | Clamping voltage | |
| I _{RM} | Leakage current @ V _{RM} | 194 |
| I _{PP} | Peak pulse current | |
| V _F | Forward voltage drop | |

| | V _{BR} @ I _R | | | I _{RM} @ V _{RM} | | R _d | αΤ | C@0V Bias |
|----------------|----------------------------------|------|----|-----------------------------------|---|----------------|----------------------|--------------|
| Part Number | min. | max. | | max. | | typ. | max. | typ. |
| | v | v | mA | nA | v | Ω | 10 ⁻⁴ /°C | pF |
| ESDALC6V1-1BM2 | 6.1 | 8.0 | 1 | 100 | 3 | 0.65 | 2.5 | 22 |



Figure 1. Relative variation of peak pulse power versus initial junction temperature

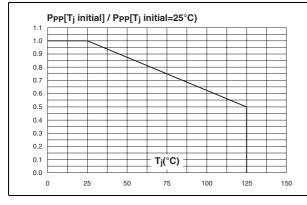


Figure 3. Clamping voltage versus peak pulse current (typical values)



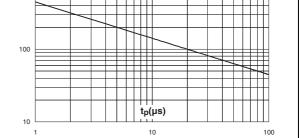


Figure 4. Junction capacitance versus reverse voltage applied (typical values)

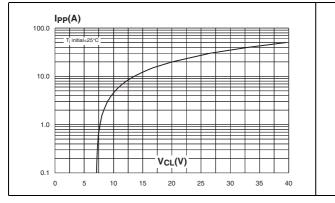


Figure 5. Relative variation of leakage current versus junction temperature (typical values)

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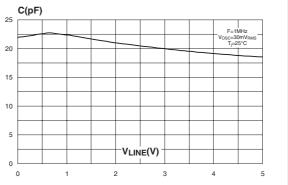


Figure 6. ESD response to IEC 61000-4-2 (+15 kV air discharge) on each channel

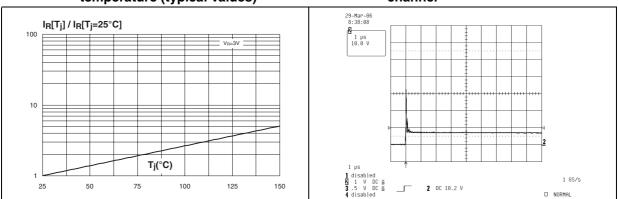


Figure 2. Peak pulse power versus exponential pulse duration

S21 attenuation measurement

Figure 7. ESD response to IEC 61000-4-2 (-15 kV air discharge) on each channel

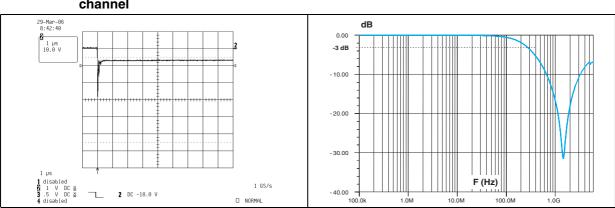
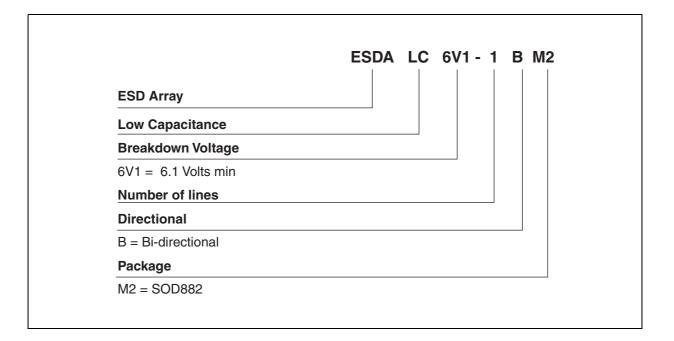


Figure 8.

result

2 Ordering information scheme

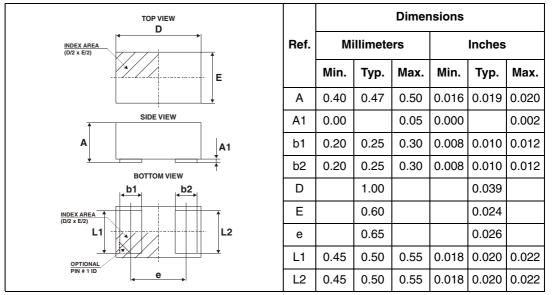




3 Package information

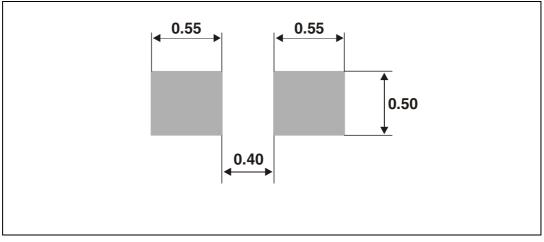
• Epoxy meets UL94, V0

Table 3.SOD-882 dimensions



Note: Product marking may be rotated by 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.





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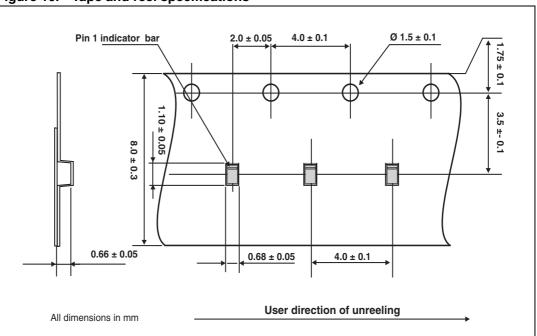


Figure 10. Tape and reel specifications

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering information

| Part number | Marking | Package | Weight | Base qty | Delivery mode |
|----------------|------------------|---------|---------|----------|---------------|
| ESDALC6V1-1BM2 | P ⁽¹⁾ | SOD-882 | 0.89 mg | 3000 | Tape and reel |

1. The marking can be rotated by 90° to diferentiate assembly location

5 Revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 11-Jan-2007 | 1 | Initial release. |



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